Application No.: 10/565,565

371(c) Date:

January 23, 2006

AMENDMENTS TO THE SPECIFICATION

Please amend Title as follows:

INORGANIC POWDER-CONTAINING RESIN COMPOSITION, FILM-FORMING MATERIAL LAYER, TRANSFER SHEET, METHOD FOR PRODUCING SUBSTRATE WITH DIELECTRIC LAYER, AND SUBSTRATE WITH DIELECTRIC LAYER AN INORGANIC POWDER-CONTAINING RESIN COMPOSITION, A FILM-FORMING MATERIAL LAYER, A TRANSFER SHEET, METHOD OF PRODUCING A SUBSTRATE HAVING A DIELECTRIC LAYER FORMED THEREON, AND A SUBSTRATE HAVING A DIELECTRIC LAYER FORMED THEREON